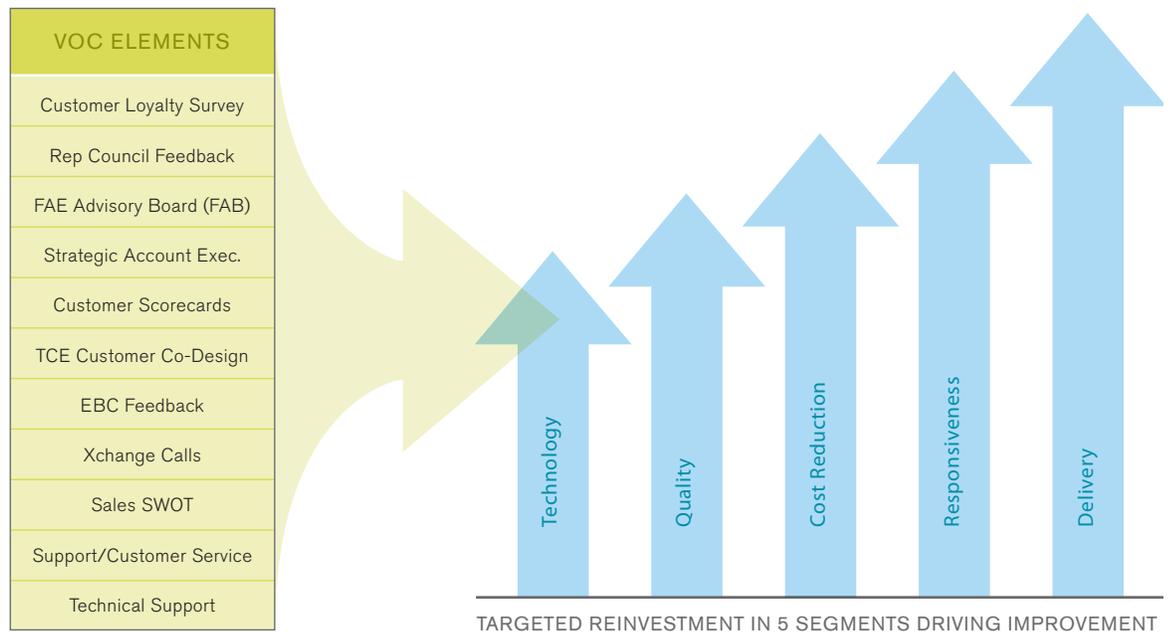


LISTENING TO THE VOICE OF THE CUSTOMER

Xilinx has a long tradition and corporate culture of customer commitment. Our path to continued success as an industry-leading semiconductor company depends on our ability to closely listen to, and understand, customer requirements.

In 2008, Xilinx launched the “Voice of the Customer” program to regularly solicit customer feedback at all levels in the organization, across different vertical markets and from all corners of the globe. We engage customers in a variety of ways across different channels, starting at the top with executive sponsorships, customer advisory councils and strategic account managers, as well as broader customer survey processes with real-time feedback mechanisms. All of this input is rolled up to Xilinx management to track Xilinx performance across technology, quality, responsiveness, delivery and cost metrics (TQRDC). Based on the favorable customer response to date, we made additional investments throughout this past year to further automate and expand the program.

XILINX QUALITY



Customer-Driven Quality

Quality unites Xilinx employees, suppliers and stakeholders in a shared mission that puts customers first. The Xilinx executive management team focuses on the quality issues that most affect our customers, and our global quality team is engaged in all aspects of our business to drive change where needed to ensure a flawless customer experience.

LISTENING TO THE VOICE OF THE CONSUMER

To ensure that we prioritize on the most important aspects of quality and better understand the root causes of quality issues, we have instituted a closed-loop, repeatable process that integrates customer interactions from multiple operations within the company to:

- *Understand top issues facing executives and engineers*
- *Analyze data points from a variety of sources*
- *Implement initiatives with metrics for measuring and reporting progress*
- *Validate results with customers directly using a quality-centric scorecard system*

We use customer data from scorecards and surveys to guide the development of quality initiatives that over time enable Xilinx to maintain technology leadership, continue to deliver products with quality for life and offer increasing value to its global customer community.

For all of 2009, Xilinx, on average, achieved all-time high scores for quality.

Expanding the Customer Voice

The primary mechanisms for collecting data have been customer scorecards from major accounts, product support surveys and direct customer interaction. In 2009, Xilinx launched a new survey process to ensure that more companies are able to provide formal feedback on all aspects of their Xilinx experience — silicon, software, IP, hardware and support.

Based on the data provided, Xilinx customer-driven quality programs for 2010 are focused in three key areas:

- *Software and IP quality*
- *Return process turnaround time in Japan*
- *Customer documentation*

To request more information or learn how you can participate in Xilinx's Voice of the Customer program, please contact us by e-mail at survey@xilinx.com.

TECHNOLOGY AND CORPORATE LEADERSHIP

Twenty-five years ago, Xilinx invented the FPGA and pioneered the fabless manufacturing model. Since then, Xilinx has established a reputation as a semiconductor industry leader that consistently delivers products on cutting-edge technologies and drives innovation that sets new standards for quality. Below is a sampling of the awards that Xilinx has garnered in recent years. We feel they underscore our company's unwavering commitment to you, our customers, through technology excellence and corporate leadership.

XILINX QUALITY

2007-2009 INDUSTRY AWARDS	XILINX RECIPIENT	AWARD SPONSOR
Most Respected Public Fabless Company	Xilinx Corporate	Global Semiconductor Alliance (third award in seven years)
ALICE Industrial Collaboration	Xilinx Corporate	CERN
100 Best Corporate Citizens	Xilinx Corporate	CRO/Business Ethnic Magazine (three consecutive years)
Top 25 Microchips that Shook the World	Industry's first FPGA in 1985 XilinxXC2064FPGA	IEEE Spectrum
100 Best Corporate Citizens	Xilinx Corporate	CRO/Business Ethnic Magazine
Company of the Year Finalist	Xilinx Corporate	EE Times China
LEED Green Building Certification	Xilinx North America HQ	U.S. Green Building Council
ASEAN Energy Awards	Xilinx Asia-Pacific HQ	ASEAN Centre for Energy
PUB Appreciation Certificate	Xilinx Asia-Pacific HQ	Public Utilities Board, Singapore
Universal Design Award for Built Environment (Silver)	Xilinx Asia-Pacific HQ	Singapore Ministry of National Development
Green Mark Platinum Award	Xilinx Asia-Pacific HQ	Singapore Ministry of National Development
Best Product of the Year	Virtex®-5 FXT FPGA	EDN China
Leading Product of the Year	ISE® 10.1 Design Tools	EDN China
Top 10 China Influential Embedded System Finalist	Virtex-5 FXT FPGA MicroBlaze™ v7 Processor AccelDSP™ and System Generator for DSP Tools	EEPW China
Editor's Choice Award	Spartan®-3A FPGA	Portable Design Magazine
Influential Embedded System New Technology Award	Spartan-3A DSP FPGA	EEPW China
Top 10 China Influential Embedded System	Virtex-5 FPGAs	EEPW China
Digital IC Product of the Year	Virtex-5 LXT FPGAs	EDN China
Semiconductor Product of the Year	Virtex-5 LXT FPGA Platform	Elektra Awards
Hot 100 Products	Spartan-3AN FPGA Platform	EDN Magazine
Best of 2007 EDA/FPGA Tool	ISE 9.1i Design Tools	Electronic Design Magazine
Design Vision Award	PlanAhead™ 8.2 Software	IEC
Product & Innovation of the Year	Virtex-5 FPGA	EDN Magazine
Design Team of the Year	Virtex-5 FPGA Design Team	EDN Magazine
Product of the Year	Virtex-5 FPGA	EE Times China
Ultimate Product Finalist	Virtex-5 FPGA PlanAhead 8.2 Software	EE Times ACE Awards
Most Innovative Product of Year	Virtex-5 FPGA	Electronique Magazine

CUSTOMER SATISFACTION & QUALITY AWARDS	
Anritsu	Top Supplier Award, 2009
Brocade	Quality Excellence Award, 2009
Datang Mobile	Core Partner Award, 2008
General Dynamics	Strategic Supplier Award, 2008
Harman Becker	Top 10 Percent Semiconductor Supplier Award, 2008
Huawei	Core Partner & Most Valued Supplier Awards, 2008 Gold Supplier Award, 2009
Motorola	Preferred Supplier Award, 2009
Sony	Quality Award, 2008
Spirent	Supplier of the Year, 2008
Tellabs	Perfect 20/20 Quality Score, 2008
ZTE	Best Supplier Award, 2008-2009 Best Technological Cooperation Award, 2009

XILINX QUALITY RESOURCE GUIDE

Xilinx publishes a comprehensive range of information about its global quality programs, metrics and documentation. The following tables provide direct links to the detailed reports and reference sites accessible to Xilinx customers either by request or online, as well as to sites for Xilinx support, training, services and third-party programs.

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DOCUMENT TITLE	AVAILABILITY
Xilinx Quality	http://www.xilinx.com/products/quality/index.htm
Quality Policy	http://www.xilinx.com/products/quality/Xilinx_Quality_Policy.pdf
Quality Manual	http://www.xilinx.com/products/quality/QualityManual.pdf
Quality Certifications	See links to documentation for each of the following certifications at http://www.xilinx.com/products/quality/index.htm ISO 9001:2000 / TL 9000 (XSJ, XAQ, XIR, XAP), ISO 9001:2000 (XCO) ISO/TS 16949:2002 (XSJ), ISO/TS 16949:2002 (XAQ) ISO/TS 16949:2002 (XIR), ISO/TS 16949:2002 (XAP) QML per MIL-PRF-38535, ISO 14001:2004 (XSJ), ISO 14001:2004 (XIR), ISO 14001:2004 (XAP), OHSAS 18001:2007 (XIR, XSJ, XAP), MIL-PRF-38535
Annual Quality Report 2009	http://xilinx.com/quality
Annual Quality Report 2008	http://xilinx.com/quality
Supplier Management	http://www.xilinx.com/products/quality/submgmt.htm
Device Reliability Report (quarterly)	http://www.xilinx.com/support/documentation/user_guides/ug116.pdf
Product Characterization Reports	Available upon request to: http://www.xilinx.com/support/techsup/tappinfo.htm
Silicon Stepping	http://www.xilinx.com/products/quality/silicon-stepping.htm
Pb-Free and RoHS-Compliant Products	http://www.xilinx.com/system_resources/lead_free/index.htm
FPGA Design Best Practices	http://www.xilinx.com/products/quality/fpga_best_practices.htm
Product Change Notifications	http://www.xilinx.com/support/documentation/customer_notices.htm
RMA and Returns Instructions	http://www.xilinx.com/products/quality/rma.htm

XILINX SITE	DIRECT LINK
Xilinx Home Page	http://www.xilinx.com/
Xilinx Support	http://www.xilinx.com/support/mysupport.htm
Training	http://www.xilinx.com/support/education-home.htm
Documentation	http://www.xilinx.com/support/documentation/index.htm
Downloads	http://www.xilinx.com/support/download/index.htm
Troubleshooting	http://www.xilinx.com/support/troubleshoot.htm
Answer Browser	http://www.xilinx.com/support/answers/index.htm
Forums	http://forums.xilinx.com/xlnx/
Publications	http://www.xilinx.com/publications/index.htm
Events	http://www.xilinx.com/events/index.htm
Webcasts	http://www.xilinx.com/events/webcasts.htm
Xilinx Services	http://www.xilinx.com/support/gsd/index.htm
Third-Party Alliances	http://www.xilinx.com/alliance/index.htm
University Program	http://www.xilinx.com/univ/
Contact Us	http://www.xilinx.com/company/contact.htm

RELIABILITY FAILURE RATE SUMMARY

The failure rate is typically defined in FIT units. One FIT equals one failure per 1 billion device hours. For example, five failures expected out of 1 million components operating for 1 thousand hours means a failure rate of five FIT. The following is the failure rate calculation method.

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$$\text{Failure Rate} = \frac{X^2 10^9}{2(\text{No. of Devices})(\text{No. of Hours})(\text{Acc. Factor})}$$

Where: X^2 = Chi-squared value at a desired confidence level and $(2f + 2)$ degrees of freedom, where f is the number of failures

The acceleration factor is calculated using the Arrhenius relationship:

$$A = \exp \left\{ \frac{E_a}{k \left(\frac{1}{T_{J1}} - \frac{1}{T_{J2}} \right)} \right\}$$

Where: E_a = Thermal activation energy (0.7eV is assumed and used in failure rate calculation except for EPROM in which 0.58 eV is used)

A = Acceleration factor

k = Boltzmann's constant, 8.617164×10^{-5} eV/°K

T_{J1} = Use junction temperature in kelvin (°K = °C + 273.16)

T_{J2} = Stress junction temperature in kelvin (°K = °C + 273.16)

PROCESS TECHNOLOGY	DEVICE HOURS AT $T_j = 125^\circ \text{C}$	FIT
0.065 μm	2,636,842	10
0.09 μm	9,718,259	1
0.13 μm	2,187,156	5
0.15 μm (FPGA)	3,150,650	8
0.15 μm (EPROM)	2,110,352	12
0.18/0.15 μm	2,554,319	10
0.18 μm	3,807,046	14
0.22/0.18 μm	2,029,156	13
0.22 μm	2,121,902	6
0.25 μm	3,102,915	4
0.35 μm / 0.25 μm	2,072,214	6
0.35 μm	4,456,867	15
0.35 μm (EPROM)	1,026,686	24
0.5 μm	2,084,780	12
0.6 μm	813,892	14
0.6 μm (EPROM)	1,057,908	23

1. FIT is calculated based on 0.7 eV (0.58 eV for EPROM), 60% C.L. and T_j of 55°C.

2. Table contains Q3 CY2009 data. For the most current quarterly report, go to http://www.xilinx.com/support/documentation/user_guides/ug116.pdf

XILINX QUALITY TRENDS

Xilinx pushes the boundaries of technology to raise the bar for quality and innovation. We continue to develop new methods and standards that make it possible to deliver superior solutions with greater efficiency to the 20,000 customers we serve across diverse markets.

XILINX QUALITY

QUALITY FOCUS	CALENDAR YEAR 2009 RESULTS	QUALITY IMPROVEMENT FACTORS
Overall Quality	<ul style="list-style-type: none"> ➤ No major customer recalls in more than four years ➤ PPM levels achieving targets ➤ Faster time to market with 40/45nm technologies 	<ul style="list-style-type: none"> ➤ Expanded strong Maverick controls ➤ Implemented spatial outlier elimination ➤ Enhanced qualification methodologies earlier in development cycle ➤ Expanded product testing and coverage ➤ Improved new products process and release criteria with each new generation—leveraged learning from 65nm technology
Fab Quality	<ul style="list-style-type: none"> ➤ 90nm defect density: <ul style="list-style-type: none"> ▪ 12% improvement from 2008 ➤ 65nm defect density: <ul style="list-style-type: none"> ▪ 23% improvement from 2008 	<ul style="list-style-type: none"> ➤ Continued improvement of statistical process control ➤ Robust in-line defect reduction
Assembly Quality	<ul style="list-style-type: none"> ➤ Sustained greater than 99% assembly yields ➤ Mechanical AOQL PPM achieving targets ➤ Completed RoHs and REACH offerings 	<ul style="list-style-type: none"> ➤ Direct materials control ➤ Failure mode effects analysis (FMEA) ➤ Commitment to environmentally friendly packaging
Test Quality	<ul style="list-style-type: none"> ➤ Electrical AOQL PPM achieving targets and sustained 0 PPM over multiple quarters ➤ Test coverage at 99% 	<ul style="list-style-type: none"> ➤ Design-for-test (DFT) ➤ Built-in self-test (BIST) ➤ Software optimization for test ➤ Continued improvement of process control

QUALITY INDUSTRY CERTIFICATIONS

Xilinx is the:

- Only PLD supplier to achieve both TL9000 and TS16949 certifications
- First PLD supplier to achieve TL9000 certification
- First fabless company to achieve TS16949 certifications

XILINX QUALITY

XILINX FACILITY	QUALITY CERTIFICATION	CERTIFIED SINCE
San Jose, California	TL9000 / ISO 9001:2000	January 2004
	ISO / TS16949:2002	March 2005
	ISO 14001:2004	August 2002
	OHSAS18001	October 2008
Dublin, Ireland	TL9000 / ISO 9001:2000	January 2004
	ISO / TS16949 2002	March 2005
	ISO 14001:2004	August 1999
	OHSAS18001	October 2008
Singapore	TL9000 / ISO 9001:2000	January 2005
	ISO / TS16949 2002	March 2005
	ISO 14001:2004	August 2006
	OHSAS18001	October 2008
Albuquerque, New Mexico	TL9000 / ISO 9001:2000	January 2005
	ISO / TS16949 2002	March 2005
Denver, Colorado	ISO9001	December 2004
Hyderabad, India	TS16949:2002	November 2008

XILINX SUPPLIERS	QUALITY CERTIFICATION	SUPPLIER RELATIONSHIP
UMC, Hsinchu, Taiwan	TS16949:2002	Foundry
Toshiba, Japan	ISO9001:2000	
Samsung, Korea	TS16949:2002/TL9000	
Amkor, Korea	TS16949:2002	Assembly and Test
Amkor, Phillipines	TS16949:2002	
STATS ChipPAC	TS16949:2002	
SPIL	TS16949:2002	